TOSHIBA TD62308AP/F/AF

TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

TD62308AP, TD62308F, TD62308AF

4CH LOW INPUT ACTIVE HIGH-CURRENT DARLINGTON SINK DRIVER

The TD62308AP/F/AF are non-inverting transistor array

which are comprised of four NPN darlington output stages and PNP input stages.

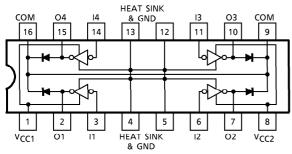
These devices are low level input active driver and are suitable for operation with TTL, 5V CMOS and 5V Microprocessor which have sink current output drivers. Applications include relay, hammer, lamp and stepping moter drivers.

FEATURES

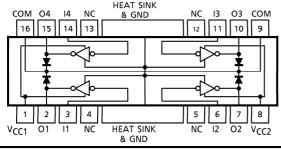
- Output current (single output) 1.5A (Max.)
- 35V (Min.) (TD62308F) 50V (Min.) High sustaining voltage output (TD62308AP, TD62308AF)
- Output clamp diodes
- Input compatible with TTL and 5V CMOS
- Low level active inputs
- Standard supply voltage
- Two V_{CC} terminals V_{CC1}, V_{CC2} (separeted)
- GND and SUB terminal = heat sink
- Package type-AP : DIP-16pin Package type-F, AF : PFP-16pin

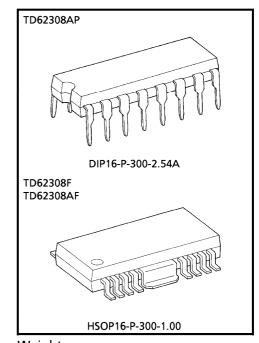
PIN CONNECTION (TOP VIEW)

TD62308AP



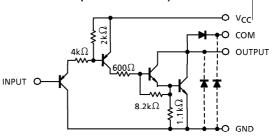
TD62308F, TD62308AF





Weight DIP16-P-300-2.54A : 1.11g (Typ.) HSOP16-P-300-1.00 : 0.50g (Typ.)

SCHEMATICS (EACH DRIVER)



(Note) The input and output parasitic diodes cannot be used as clamp diodes.

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MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	С	SYMBOL	RATING	UNIT	
Supply Voltage		V _{CC}	-0.5~10	V	
Output Sustaining	F		-0.5~35	V	
Voltage	AP, AF	VCE (SUS)	-0.5~50		
Output Current		IOUT	1.5	A / ch	
Input Current		IN	– 10	mΑ	
Input Voltage		v_{IN}	-0.5~30	V	
Clamp Diode Reverse	F	V-	35	٧	
Voltage	AP, AF	V _R	50		
Clamp Diode Forward	Current	ΙF	1.5	Α	
Davis Dissipation	AP	D-	1.47 / 2.7 (Note 1)	w	
Power Dissipation	F, AF	P_{D}	0.9 / 1.4 (Note 2)		
Operating Temperature	e	T _{opr}	- 40∼85	°C	
Storage Temperature		T _{stg}	- 55~150	°C	

(Note 1) On Glass Epoxy ($50 \times 50 \times 1.6$ mm Cu 50%)

(Note 2) On Glass Epoxy $(60 \times 30 \times 1.6 \text{mm Cu } 30\%)$

RECOMMENDED OPERATING CONDITIONS (Ta = $-40 \sim 85$ °C)

CHARACTERISTIC		SYMBOL	CONDITION		MIN.	TYP.	MAX.	UNIT		
Supply Voltage			Vcc	— 4.5 — 5. :		5.5	V			
Output Sustaining F Voltage AP, AF		V-= (0.10)	_		0	_	35	V		
		AP, AF	VCE (SUS)	_		0	_	50	v	
				DC 1 circuit, Ta = 25°C		0	_	1250		
Output Current		AP	^I оит	T _{pw} = 25ms 4 circuits Ta = 85°C	Duty = 10%	0	_	1250	mA / ch	
					Duty = 50%	0	_	700		
		- A			Duty = 10%	0	_	1250		
		F, AF		T _j = 120°C	Duty = 50%	0	_	390		
Input Voltage	ut Voltage		VIN	_		0	_	25	V	
1	Οι	utput On	VIN (ON)	1		0	_	V _{CC} - 3.6	v	
Input Voltage	Οι	utput Off	V _{IN} (OFF)	_	_	V _C C – 1.0	_	-3.6 V _C C	v	
Clamp Diode		F	\/-	_		_	_	35	V	
Reverse Voltage AP, AF		V_{R}	_		_	_	50	\ \ \		
Clamp Diode Forv	var	d Current	Ιϝ	_	-	_	_	1.25	Α	
Power Dissipation	AP		D_	Ta = 85°C (Note 1)		_		1.4	w	
Power Dissipation	l	F, AF	PD	Ta = 85°C (Note	2)	T - T - T		0.7] vv	

(Note 1) On Glass Epoxy ($50 \times 50 \times 1.6$ mm Cu 50%)

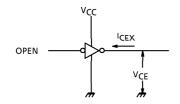
(Note 2) On Glass Epoxy $(60 \times 30 \times 1.6 \text{mm Cu } 30\%)$

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

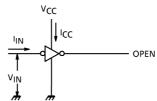
ELECTRICAL CHARA		<u> </u>							
CHARACTERISTIC		SYMBOL	TEST CIR- CUIT	TEST CONDITION		MIN.	TYP.	MAX.	UNIT
Output Leakage Current	AP, AF	ICEX	1	V _{CE} = 50V, Ta = 25°C		_	_	50	μΑ
	AP, AF			V _{CE} = 50V, Ta = 85°C V _{CE} = 35V, Ta = 25°C		_	_	100	
	F					_		50	
				$V_{CE} = 35V, T_{CE} = 35V, $			_	100	
Output Saturation	Output Saturation Valtage		3	I _{OUT} = 1.25A		_	_	1.8	\ \
Output Saturation Voltage		VCE (sat)		I _{OUT} = 0.7A		_	_	1.3	V
Input Voltage	"H" Level	V _{IH}	_	_		V _C C – 1.6	_	25	V
	"L" Level	V _{IL}	_	_		_	_	V _С С – 3.6	
Input Current	"H" Level	lіН	-	_		_	_	10	μΑ
	"L" Level	Ι _Ι L				_	- 0.05	- 0.36	mΑ
Clamp Diode	AP, AF	la.	1	$V_R = 50V, Ta = 25^{\circ}C$ $V_R = 35V, Ta = 25^{\circ}C$		_	_	50	μ A
Reverse Current	F	I _R						50	
Clamp Diode Forw	de Forward Voltage V _F 5 I _F = 1.25A —		_	1.5	2.0	V			
Supply Current	Output On	ICC (ON)	2	$V_{CC} = 5.5V, \ V_{IN} = 0V$		_	8.5	12.5	mA / ch
	Output Off	ICC (OFF)		$V_{CC} = 5.5V$, $V_{IN} = V_{CC}$		_		1.0	μ A
Turn-On Delay	F	t _{ON}	- 6		$V_{OUT} = 35V$ $R_L = 28\Omega$		0.2	_	- μ\$
	AP, AF			C _L = 15pF	$V_{OUT} = 50V$ $R_L = 40\Omega$		Ų.Z		
Turn-Off Delay	F	torr		CL = 13\$1	$V_{OUT} = 35V$ $R_L = 28\Omega$	_	5.0	_	
	AP, AF	tOFF			$V_{OUT} = 35V$ $R_L = 40\Omega$		3.0		

TEST CIRCUIT

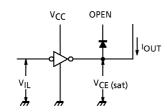
1. I_{CEX}



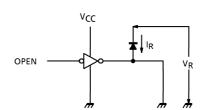
2. I_{CC}



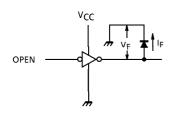
3. VCE (sat)



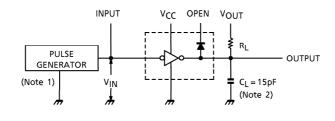
4. I_R

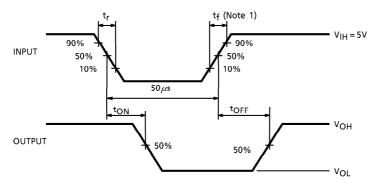


5. V_F



6. ton, toff

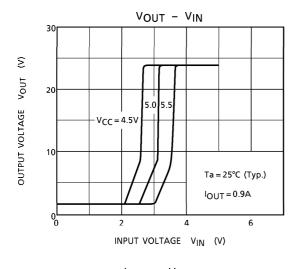


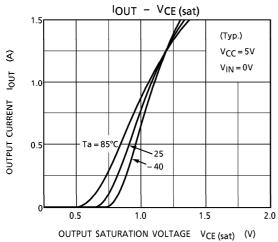


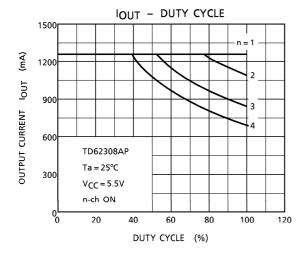
- (Note 1) Pulse width 50μ s, duty cycle 10%
 - Output impedance 50Ω $t_r \le 5$ ns, $t_f \le 10$ ns
- (Note 2) C_L includes probe and jig capacitance.

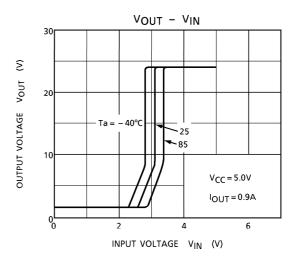
PRECAUTIONS for USING

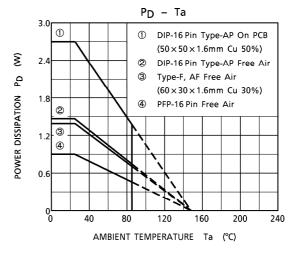
Utmost care is necessary in the design of the output line, V_{CC} , COMMON and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.

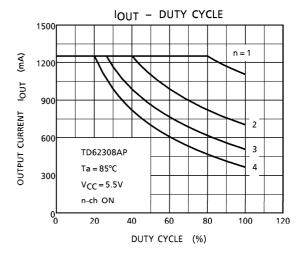


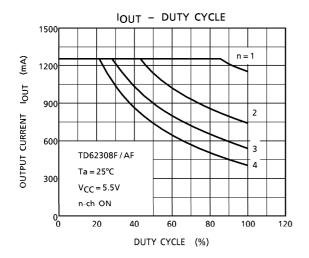


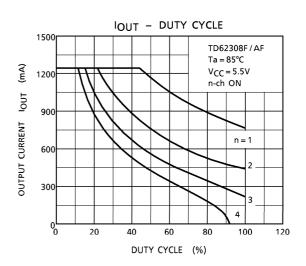






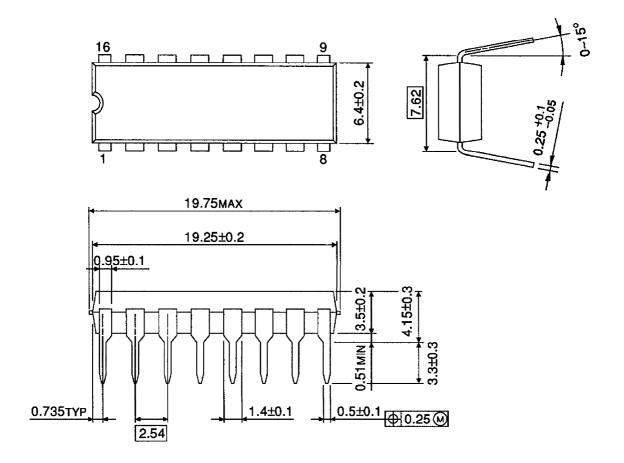






OUTLINE DRAWING DIP16-P-300-2.54A

Unit: mm

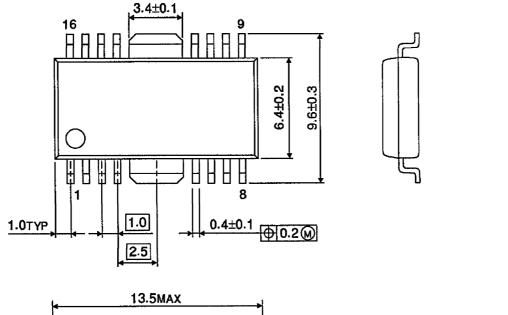


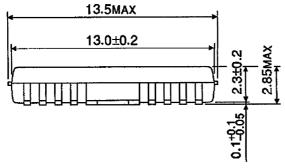
Weight: 1.11g (Typ.)

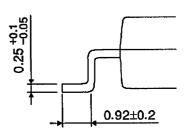
OUTLINE DRAWING

HSOP16-P-300-1.00

Unit: mm







Weight: 0.50g (Typ.)